

Description

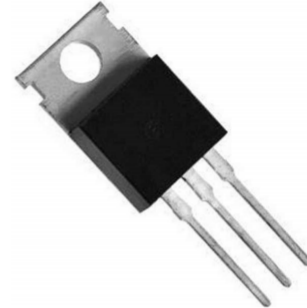
The IRF9530-ML uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. It is ESD protected.

General Features

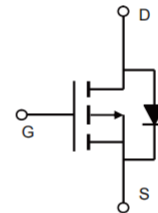
- $V_{DS} = -100V, I_D = -13A$
 $R_{DS(ON)} < 200m\Omega @ V_{GS} = -10V$ (Typ:170m Ω)
- Super high dense cell design
- Advanced trench process technology
- Reliable and rugged
- High density cell design for ultra low on-resistance

Application

- Power switch
- DC/DC converters



TO-220



Schematic

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	-13	A
Drain Current-Continuous($T_C = 100^\circ C$)	$I_D(100^\circ C)$	-9.2	A
Pulsed Drain Current	I_{DM}	-52	A
Maximum Power Dissipation	P_D	40	W
Derating factor		0.27	W/ $^\circ C$
Single pulse avalanche energy ^(Note 5)	E_{AS}	110	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta jc}$	3.75	°C/W
--	-----------------	------	------

Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

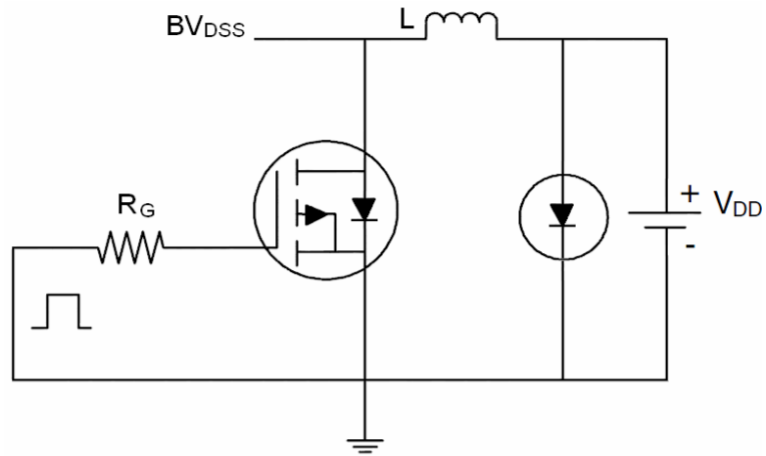
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-100	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-100V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 10	μA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.9	-3	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-10A$	-	170	200	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_D=-10A$	12	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=-50V, V_{GS}=0V,$ $F=1.0\text{MHz}$	-	1734	-	PF
Output Capacitance	C_{oss}		-	86	-	PF
Reverse Transfer Capacitance	C_{rss}		-	40	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-50V, I_D=-10A$ $V_{GS}=-10V, R_{GEN}=9.1\Omega$	-	12	-	nS
Turn-on Rise Time	t_r		-	52	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	28	-	nS
Turn-Off Fall Time	t_f		-	38	-	nS
Total Gate Charge	Q_g	$V_{DS}=-50V, I_D=-10A,$ $V_{GS}=-10V$	-	33.1	-	nC
Gate-Source Charge	Q_{gs}		-	4.2	-	nC
Gate-Drain Charge	Q_{gd}		-	7.1	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{GS}=0V, I_S=-10A$	-	-	-1.2	V
Diode Forward Current ^(Note 2)	I_S	-	-	-	-13	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = -10A$ $di/dt = 100A/\mu\text{s}$ ^(Note 3)	-	35	-	nS
Reverse Recovery Charge	Q_{rr}		-	46	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

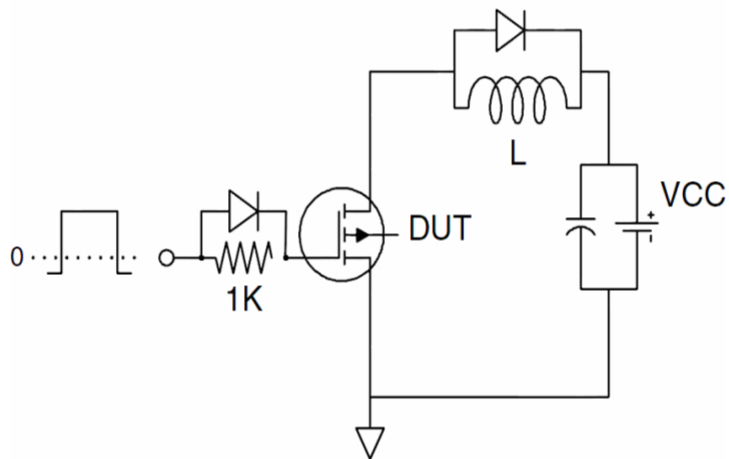
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. E_{AS} condition: $T_J=25^\circ\text{C}, V_{DD}=-50V, V_G=-10V, L=0.5\text{mH}, R_g=25\Omega$

Test Circuit

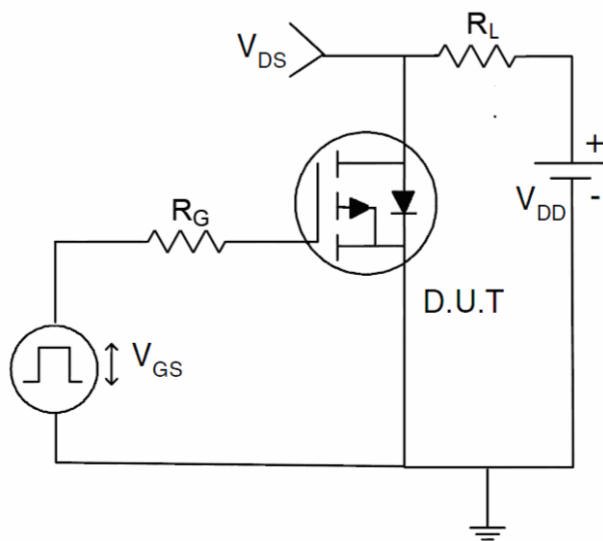
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

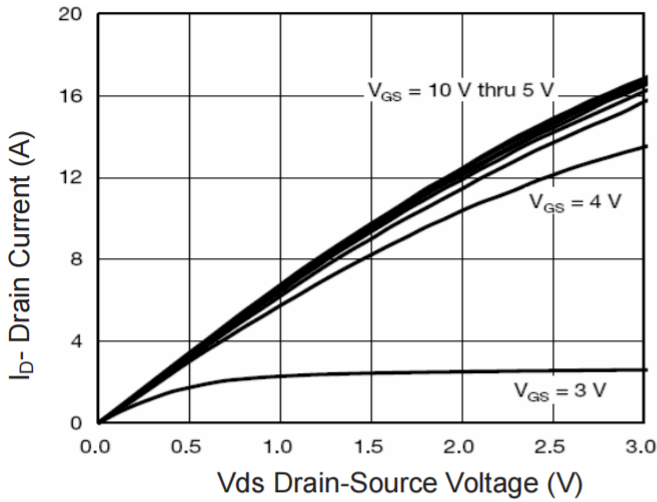


Figure 1 Output Characteristics

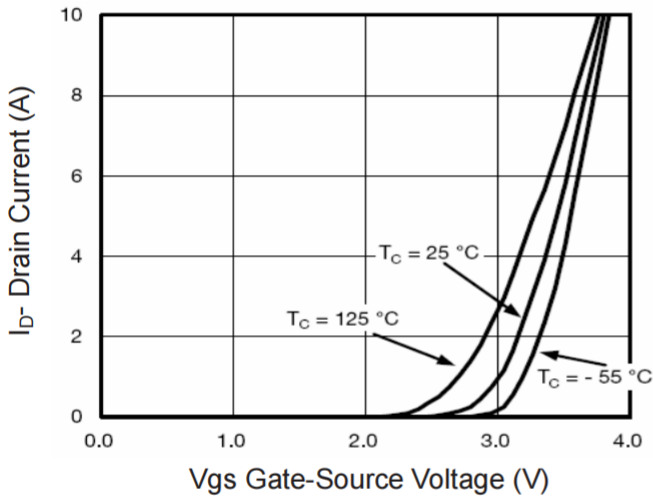


Figure 2 Transfer Characteristics

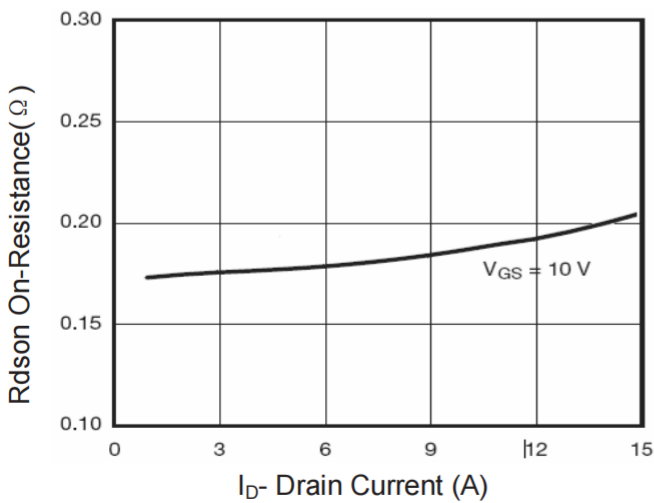


Figure 3 Rdson- Drain Current

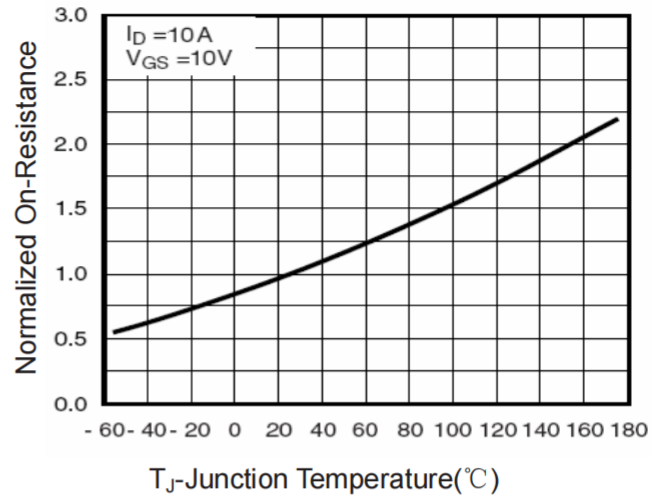


Figure 4 Rdson-Junction Temperature

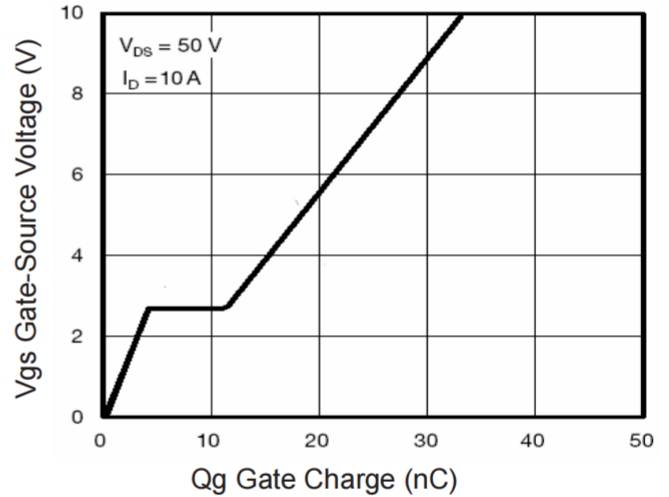


Figure 5 Gate Charge

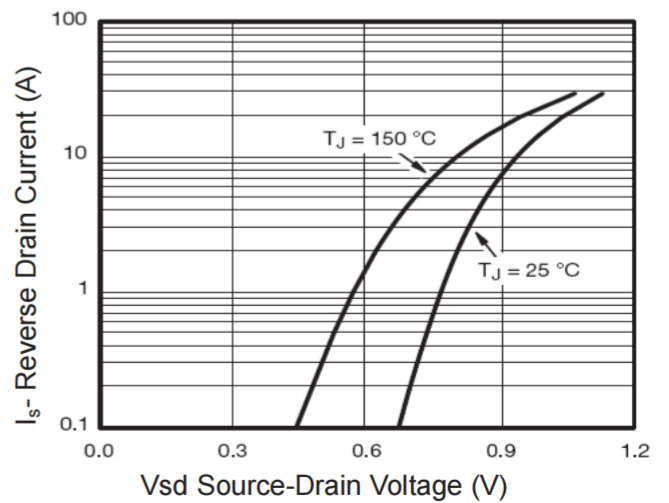


Figure 6 Source- Drain Diode Forward

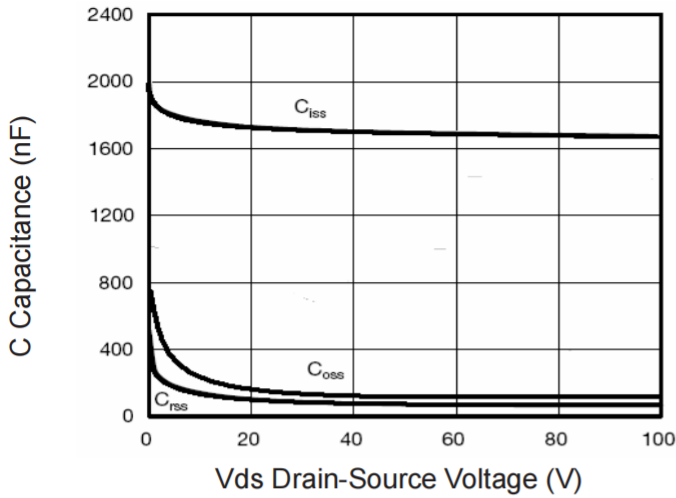


Figure 7 Capacitance vs Vds

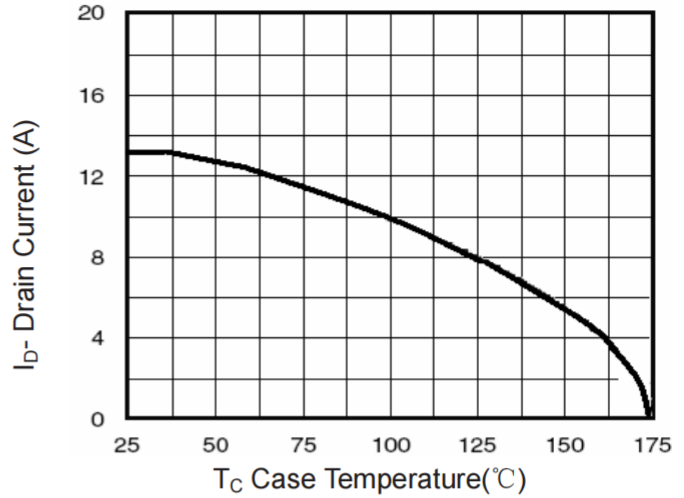


Figure 9 Drain Current vs Case Temperature

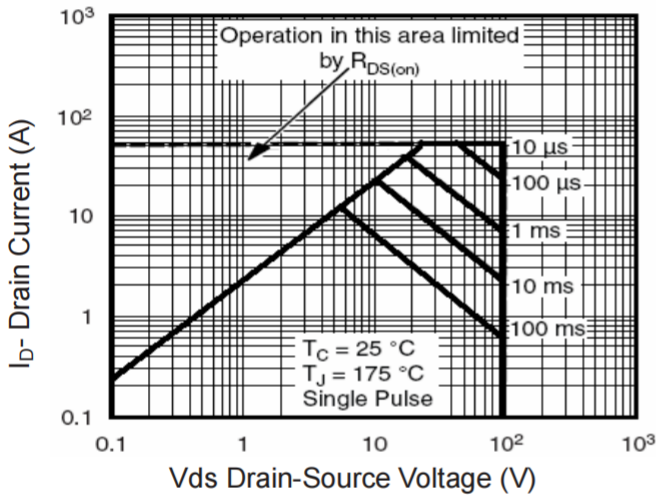


Figure 8 Safe Operation Area

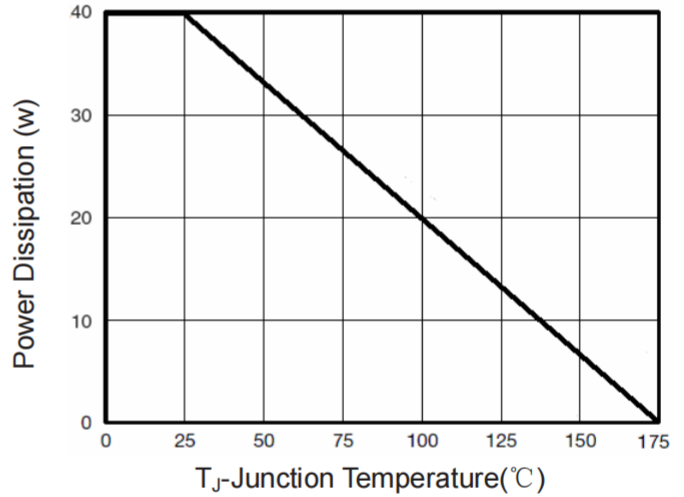


Figure 10 Power De-rating

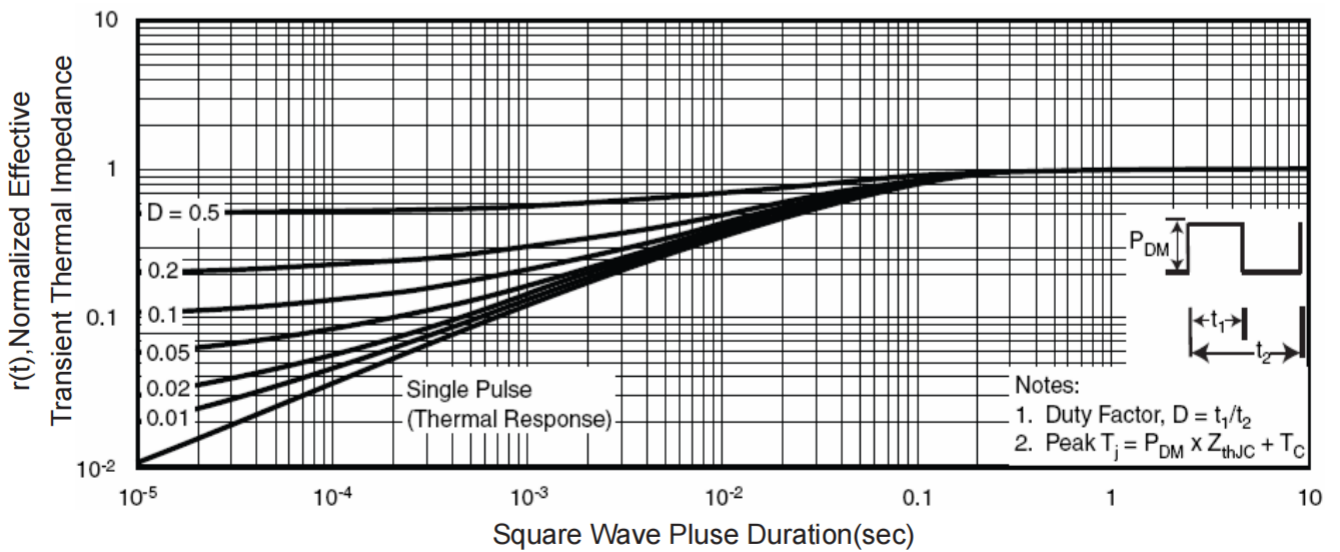


Figure 11 Normalized Maximum Transient Thermal Impedance

Disclaimer

The information presented in this document is for reference only. MOSLEADER reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), MOSLEADER or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.